

30V, 190A, 1.9mΩ N-channel Power Trench MOSFET

JMTE018N03A

Features

- $\bullet \;\;$ Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

Applications

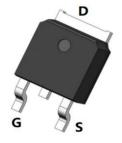
- Load Switch
- PWM Application
- Power Management

Product Summary

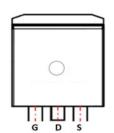
Parameters	Value	Unit
V_{DSS}	30	V
$V_{GS(th)_Typ}$	1.5	V
$I_D(@V_{GS}=10V)$	190	А
$R_{DS(ON)_Typ}(@V_{GS}=10V$	1.9	mΩ



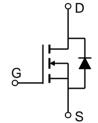




TO-263 top view



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMTE018N03A	JMTE018N03A	3	Tape&Reel	TO-263-3L	800	4000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{DS}	Drain-to-Source Voltage		30	V
V_{GS}	Gate-to-Source Voltage		±20	V
I-	Continuous Drain Current	$T_C = 25$ °C	190	^
I _D	Continuous Drain Current	$T_C = 100$ °C	135	_ A
I_{DM}	Pulsed Drain Current (1)		Refer to Fig.4	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		271	mJ
P _D		$T_C = 25$ °C	291	w
		$T_C = 100$ °C	116	T vv
T_{J}, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	35	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.4	C/VV



Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	1.5	2.0	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_D = 30A$	-	1.9	2.4	mΩ
Dynami	c Characteristics					
R_{g}	Gate Resistance	f = 1MHz	-	2.1	-	Ω
C _{iss}	Input Capacitance	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	6278	-	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 15V,$ f = 1MHz	-	863	-	pF
C_{rss}	Reverse Transfer Capacitance		-	532	-	pF
Q_g	Total Gate Charge		-	108	-	nC
Q _{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 15V, I_{D} = 30A$	-	20	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V DS = 13V, 1D = 30A	-	20	-	nC
	ng Characteristics				Ι	Г
t _{d(on)}	Turn-On DelayTime	4	-	13	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 15V$	-	29	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 30A, R_{GEN} = 3\Omega$	-	85	-	ns
t _f	Turn-Off Fall Time		-	50	-	ns
Body D	iode Characteristics			1	1	1
I _S	Maximum Continuous Body Diode Forward Current		-	-	190	Α
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	761	Α
V_{SD}	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 20A, di/dt = 100A/us	-	28	-	ns
Qrr	Body Diode Reverse Recovery Charge	$rac{1}{1}$ $rac{1}$ $rac{1}{1}$ $rac{1}{1}$ $rac{1}$ $rac{1}{1}$ $rac{1}$	-	16	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

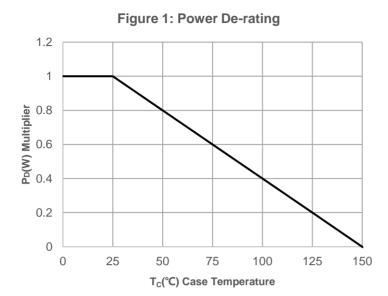
 $^{2.\;}E_{AS}\;condition:\;Starting\;T_J=25C,\;V_{DD}=15V,\;V_G=10V,\;R_G=25ohm,\;L=0.5mH,\;I_{AS}=33.04A,\;V_{DD}=0V\;during\;time\;in\;avalanche.$

^{3.} $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB.

^{4.} Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.



Typical Performance Characteristics



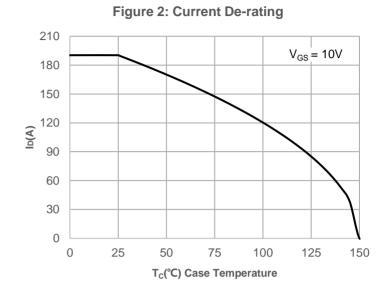
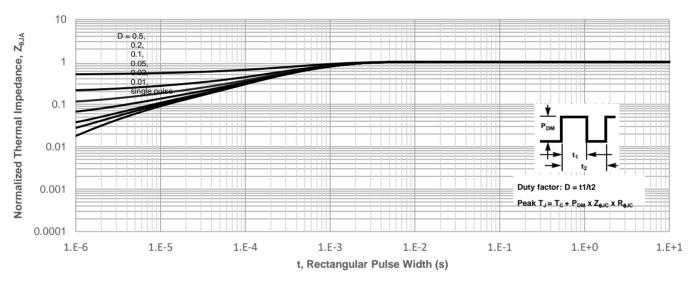
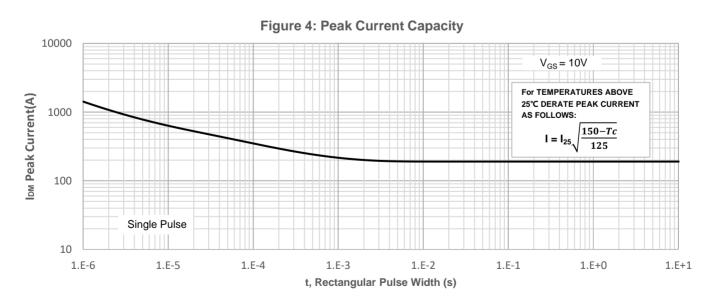


Figure 3: Normalized Maximum Transient Thermal Impedance







Typical Performance Characteristics

Figure 5: Output Characteristics

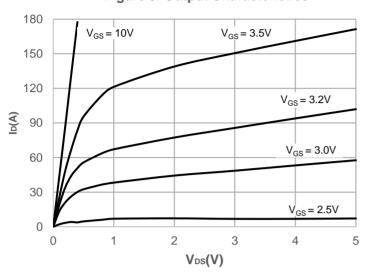


Figure 6: Typical Transfer Characteristics

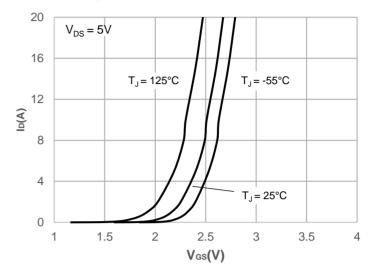


Figure 7: On-resistance vs. Drain Current

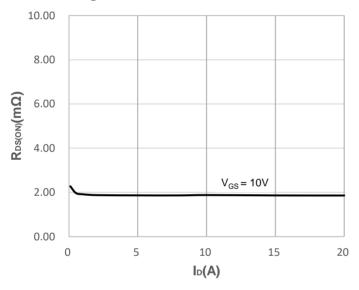


Figure 8: Body Diode Characteristics

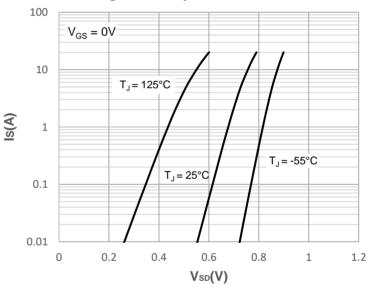


Figure 9: Gate Charge Characteristics

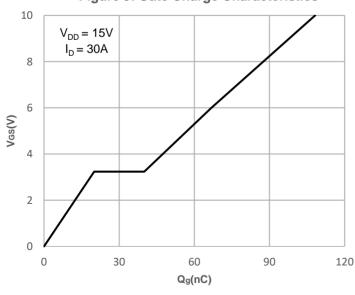
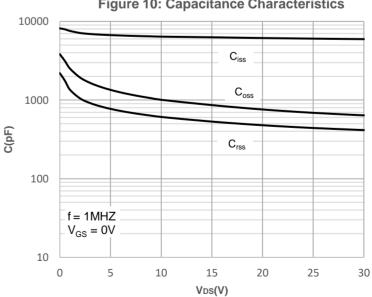


Figure 10: Capacitance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

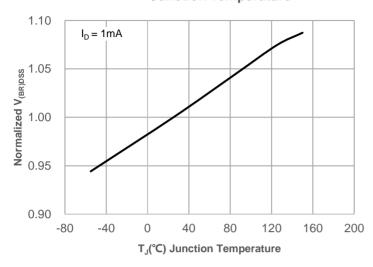


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

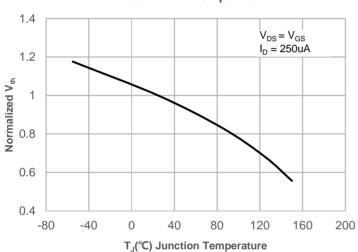


Figure 15: Maximum Safe Operating Area

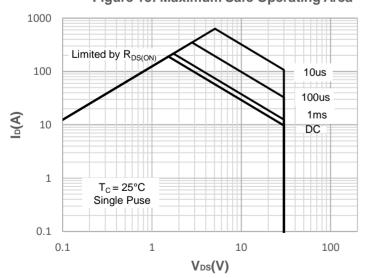
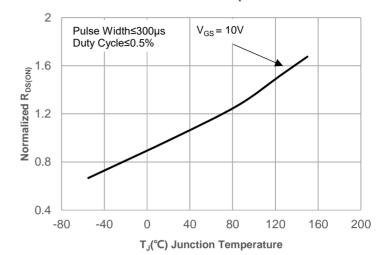
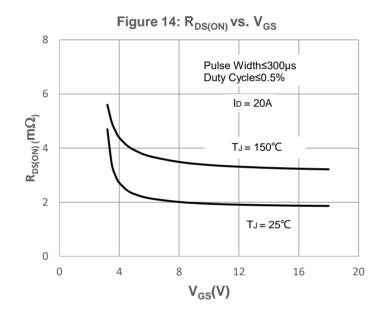


Figure 12: Normalized on Resistance vs. Junction Temperature







Test Circuit

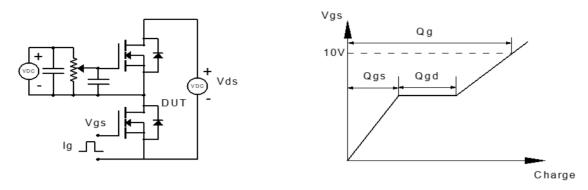


Figure 1: Gate Charge Test Circuit & Waveform

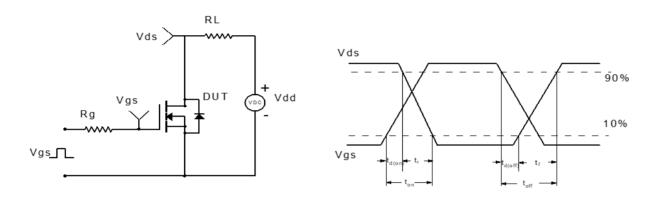


Figure 2: Resistive Switching Test Circuit & Waveform

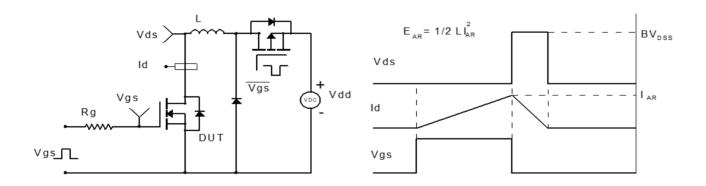


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

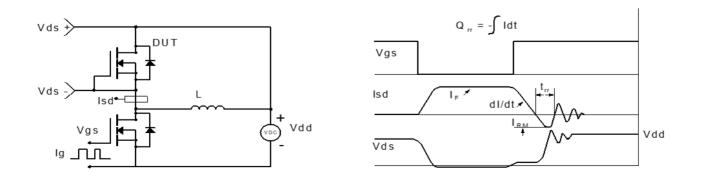
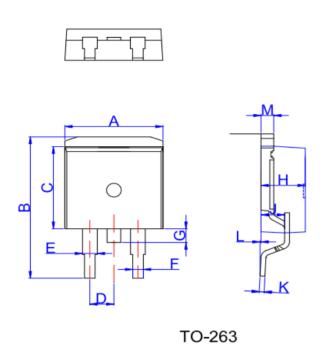


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(TO-263-3L)



			Dime	ensions		
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	9.90		10.20	0.390		0.402
В	14.70		15.80	0.579		0.622
С	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
Н	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
М	1.25		1.35	0.049		0.053

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